









PRODUCT DATASHEET



- ► PCB Side View
- ▶ 0602SV (1606) 1.1t
- ► Green (525nm)

N0G03S03SV





0602SV 1.1t Series

FEATURES:





Release Date: 13 November 2015 Version: A1.2

- Package: Side View PCB SMT Package
- Forward Current: 20mA Forward Voltage (typ.): 3.2V
- Luminous Intensity (typ.): 200mcd @20mA
- Colour: Green Wavelength: 525nm Viewing angle: 130°
- **Materials:** Die: InGaN
- Resin: Epoxy (Water Clear) Operating Temperature: -40~+85°C Storage Temperature: -40~+90°C
- **ESD:** 150V
- **Grouping parameters:**
 - Forward voltage
 - Luminous intensity
 - **Dominant Wavelength**
- Soldering methods: Reflow
- Preconditioning: acc. to JEDEC Level 3
- Packing: 8mm tape with 3000/reel, ø180mm (7")

APPLICATIONS:

- Backlighting
- Indication Light
- Side view light strip
- Switch light
- Dashboard
- Keyboard



CHARACTERISTICS:

Absolute Maximum Characteristics (Ta=25°C)

Parameter	Symbol	Ratings	Unit
Forward Current	I _F	25	mA
Peak Forward Current Duty 1/10@10KHz	I _{FP}	100	mA
Reverse Current @5V	I _R	50	μΑ
Power Dissipation	PD	110	mW
Electrostatic Discharge	ESD	150	V
Operating Temperature	T _{OPR}	-40~+85	°C
Storage Temperature	T _{STG}	-40~+90	°C

Electrical & Optical Characteristics (Ta=25°C)

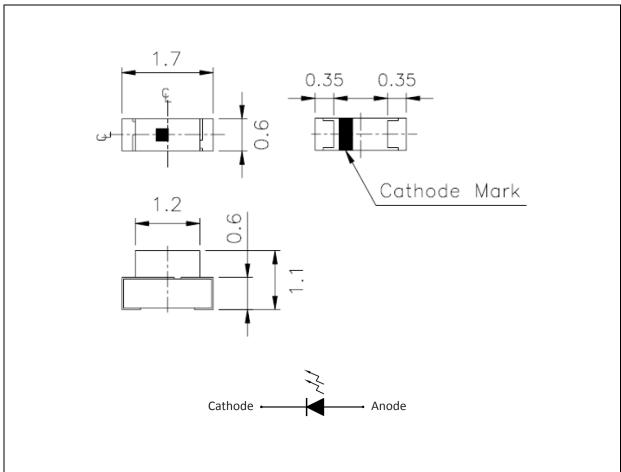
Darameter	Symbol	Values			Unit	Test
Parameter	Symbol	Min.	Тур.	Max.	Unit	Condition
Forward Voltage	V_{F}	2.7		3.7	V	I _F =20mA
Luminous Intensity	I _V	112	200	285	mcd	I _F =20mA
Dominant Wavelength	$\lambda_{\scriptscriptstyle D}$	520		535	nm	I _F =20mA
Peak Wavelength	$\lambda_{ extsf{P}}$		518		nm	I _F =20mA
Spectral Line Half Bandwidth	Δλ		35		nm	I _F =20mA
Viewing Angle	2θ _{1/2}		130		deg	I _F =20mA

^{1.} Luminous intensity (I $_{\rm V}$) ±15%, Forward Voltage (V $_{\rm F}$) ±0.1V



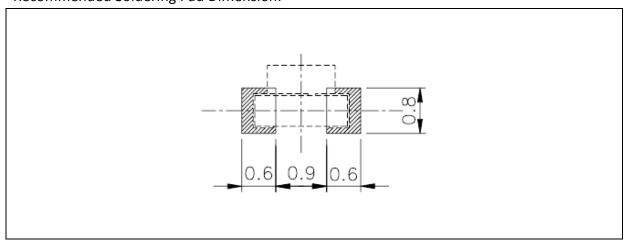
OUTLINE DIMENSION:

Package Dimension:



- 1. All dimensions are in millimetre (mm).
- 2. Tolerance ±0.2mm, unless otherwise noted.

Recommended Soldering Pad Dimension:



- 1. Dimensions are in millimetre (mm).
- 2. Tolerance ±0.1mm with angle tolerance ±0.5°.



BINNING GROUPS:

Forward Voltage Classifications (I_F = 20mA):

Code	Min. Max.		Unit
1	2.7	2.8	
2	2.8	2.9	
3	2.9	3.0	
4	3.0	3.1	
5	3.1	3.2	V
6	3.2	3.3	V
7	3.3	3.4	
8	3.4	3.5	
9	3.5	3.6	
10	3.6	3.7	

Luminous Intensity Classifications ($I_F = 20 \text{mA}$):

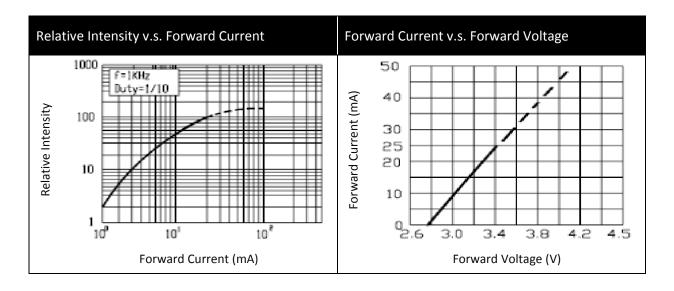
Code	Min.	Max.	Unit
R1	112	140	
R2	140	180	mad
S1	180	225	mcd
S2	225	285	

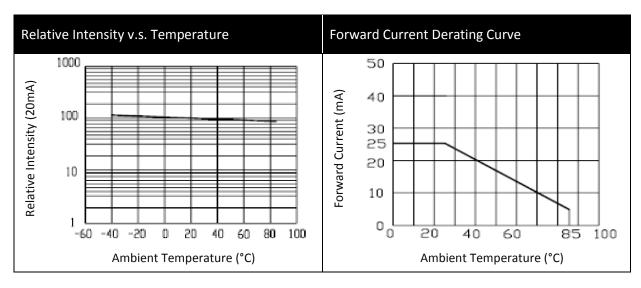
Dominant Wavelength Classifications (I_F = 20mA):

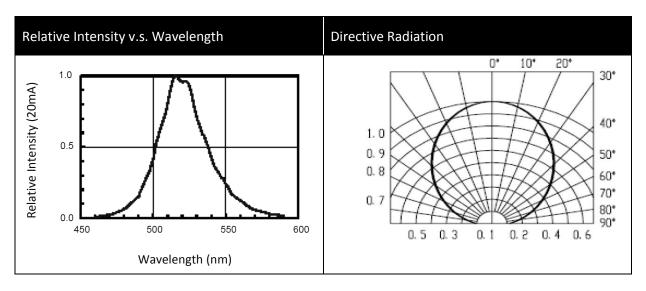
Code	Min.	Max.	Unit
X	520	525	
Υ	525	530	nm
Z	530	535	



ELECTRO-OPTICAL CHARACTERISTICS:



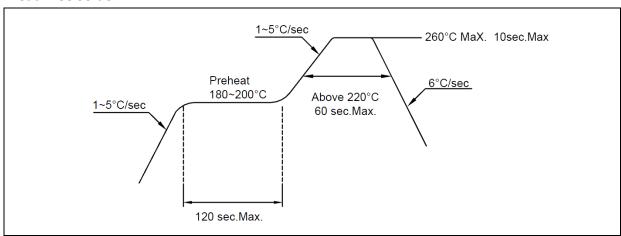






RECOMMENDED SOLDERING PROFILE:

Lead-free Solder:



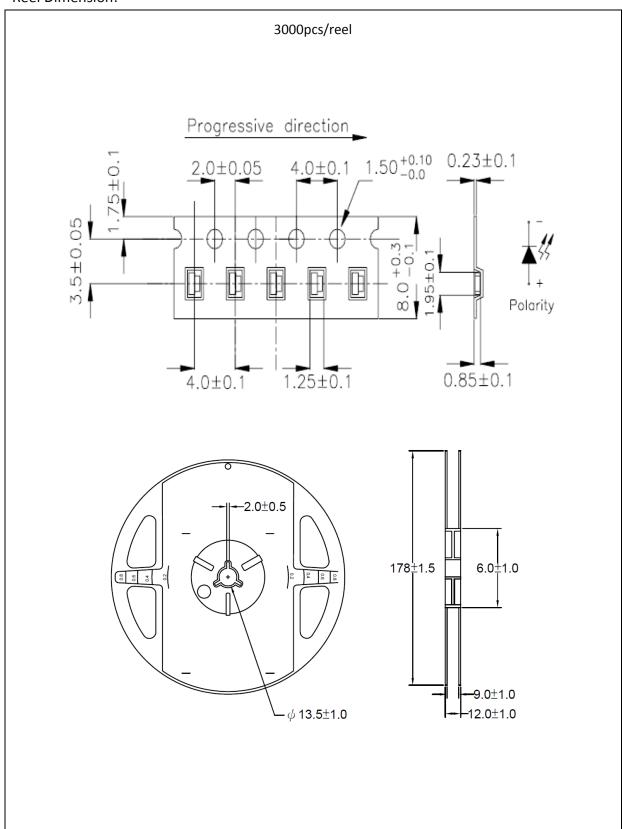
Note:

- 1. Maximum reflow soldering: 2 times.
- 2. Before, during, and after soldering, should not apply stress on the components and PCB board.



PACKING SPECIFICATION:

Reel Dimension:





PRECAUTIONS OF USE:

Storage:

It is recommended to store the products in the following conditions:

- Humidity: 60% R.H. Max.
- Temperature: 5°C~30°C (41°F ~86°F).

Shelf life in sealed bag: 12 month at 5°C~30°C and <60% R.H.

Once the package is opened, the products should be used within a week. Otherwise, they should be kept in a damp-proof box with descanting agent and apply baking at 60°C±5°C for 15hrs before use.

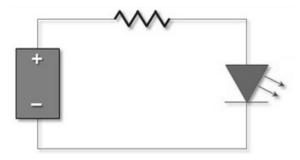
Baking:

It is recommended to bake the LED before soldering if the pack has been unsealed for longer than 24hrs. The suggested baking conditions are as followings:

- 70±3°C x 24hrs and <5%RH, taped / reel package.
- 100±3°C x 2hrs, bulk (loose) package.
- 130±3°C x 30min, bulk (loose) package.

It's normal to see slight color fading of carrier (light yellow) after baking in process.

Testing Circuit:



Must apply resistor(s) for protection (over current proof).

Cleaning:

Use alcohol-based cleaning solvents such as isopropyl alcohol to clean the LED carrier / package. Avoid putting any stress force directly on to the LED lens.

ESD (Electrostatic Discharge):

Static Electricity or power surge will damage the LED. Use of a conductive wrist band or anti-electrosatic glove is recommended when handing the LED all time. All devices, equipment, machinery, work tables, and storage racks must be properly grounded.

In the events of manual working in process, make sure the devices are well protected from ESD at any time.



REVISION RECORD:

Version	Date	Summary of Revision
A1.0	13/02/2014	Datasheet set-up.
A1.1	26/07/2014	Revise picture and specification.
A1.2	13/11/2015	Part number adds -SV for side view.